

**IN THE CLAIMS:**

Please amend the claims as follows:

1. (Currently amended) A module component comprising:  
  
a substrate made of resin having a plurality of penetration holes, said plurality of penetration holes disposed in said substrate so as to form a matrix of N aligned rows and M aligned columns of said penetration holes; each of said penetration holes being aligned in both a row and a column of said matrix, and each row and each column of said matrix comprising at least three ~~[[two]]~~ penetration holes;  
  
~~[[a]]~~ circuit wirings ~~[[wiring]]~~ disposed on both sides of said substrate, respectively; and  
  
a chip component having a height almost the same as a depth of each of said penetration holes, said chip component disposed in one of said penetration holes for electrically coupling said circuit wirings ~~[[wiring]]~~ disposed on both sides of said substrate,  
  
wherein N is equal to or greater than 3, and M is equal to or greater than 3.
2. (Cancelled)
3. (Cancelled)
4. (Previously presented) A module component according to claim 1, further comprising a fixing member for filling up a gap between said chip component and said one of said penetration holes.
5. (Previously presented) A module component according to claim 1, wherein at least one of the penetration holes is tapered.
6. (Previously presented) A module component according to claim 1, wherein support means is formed at said one of said penetration holes for supporting said chip component.

7. (Previously presented) A module component according to claim 1, further comprising an auxiliary substrate disposed over at least one side of the substrate.
8. (Currently amended) A module component comprising:  
a substrate made of resin having [[a]] penetration holes [[hole]];  
circuit wirings [[wiring]] disposed on both sides of said substrate, respectively;  
[[and]]  
a first [[and second]] auxiliary substrate and a second auxiliary substrate [[substrates]] disposed such that said substrate is disposed between said first auxiliary substrate and said second auxiliary substrate [[substrates]], and  
a chip component disposed in one of said [[the]] penetration holes [[hole]], said chip component having a predetermined [[specified]] height being greater than the depth of one of said [[the]] penetration holes [[hole]] and not projecting from said first and said second auxiliary substrate [[substrates]], said chip component electrically coupling said circuit wirings to each other [[wiring disposed on both sides of said substrate]],  
wherein said [[the]] penetration holes are [[hole is]] formed at positions [[a position]] according to a matrix.
9. (Original) A module component according to claim 1, wherein an end of said chip component and a surface of said substrate are formed in different colors.
10. (Currently amended) A module component comprising:  
a substrate made of resin having [[a]] penetration holes [[hole]];  
circuit wirings [[wiring]] disposed on both sides of said substrate, respectively;  
a chip component, having a height almost same as a depth of one of said penetration holes, and placed [[hole and put]] in [[the]] one of said penetration holes

[[hole]] for electrically coupling said circuit wirings to each other [[wiring disposed on both sides of said substrate]];

an auxiliary substrate disposed over said substrate;

an IC chip mounted on said auxiliary substrate; and

a capacitor placed [[put]] in another one of said penetration holes [[hole]]

immediately beneath said IC chip to be coupled directly with said IC chip,

wherein said [[the]] penetration holes are [[hole is]] formed at positions [[a position]] according to a matrix.

11. (Currently amended) A module component according to claim 1, further comprising a ground layer disposed beneath said substrate, said ground layer being coupled with one of said circuit wirings [[wiring]] disposed on a lower side of said substrate.

12. (Currently amended) A module component comprising:

a substrate made of resin having [[a]] penetration holes [[hole]];

circuit wirings [[wiring]] disposed on both sides of said substrate, respectively;

[[and]]

a chip component, having a height almost same as a depth of one of said penetration holes, and placed [[hole and put]] in [[the]] one of said penetration holes [[hole]] for electrically coupling said circuit wirings to each other [[wiring disposed on both sides of said substrate]];

an auxiliary substrate disposed over said substrate;

an IC chip mounted on said auxiliary substrate; and

a ground layer disposed beneath said substrate,

wherein the penetration holes are [[hole is]] formed at positions [[a position]]  
according to a matrix;

[[wherein a chip component having a specific value is accommodated to compose  
a desired circuit;]] and

wherein said IC chip is coupled directly with said ground layer.

13. (Withdrawn) A manufacturing method according to a module component  
comprising the steps of:

forming a penetration hole on a substrate made of resin;

inserting a chip component into the penetration hole, the chip component having  
an almost same height as a depth of the penetration hole;

forming a circuit wiring for coupling the chip component on said substrate; and

heating, compressing, and adhering an auxiliary substrate on at least one of both  
sides of the substrate,

wherein the penetration hole is formed according to a specified rule, and a chip  
component of a specific value is accommodated to compose a desired circuit.

14. (Withdrawn) A manufacturing method according to claim 13, wherein said step of  
forming the penetration hole comprises forming the penetration hole at a specified position  
according to a matrix, and a chip component of a specific value is put in the penetration hole  
to compose a desired circuit.

15. (Withdrawn) A manufacturing method according to claim 13, wherein said step of  
forming the penetration hole comprises the step of forming the penetration holes according  
to a matrix, and wherein said step of inserting the chip component comprises the step of

inserting the chip component of a specific value in a specified penetration hole to compose a desired circuit.

16. (Withdrawn) A module component comprising:  
a molded element with a chip component molded said resin with resin, an end electrode of said chip component being exposed; and  
a circuit wiring on at least one side of said molded elements,  
wherein said chip component is disposed according to a specified rule, and said chip component is molded with said resin to compose a desired circuit.
17. (Withdrawn) A module component according to claim 16, wherein said chip component is disposed at a specified position according to a matrix, and said chip component is molded with said resin to compose a desired circuit.
18. (Withdrawn) A module component according to claim 17 further comprising a dummy component having a same size as said chip component disposed at a position not filled with said chip component according to the matrix.
19. (Withdrawn) A module component according to claim 16, wherein said molded element is molded with one of epoxy resin and phenol resin.
20. (Withdrawn) A module component according to claim 16, wherein said resin contains a filler having at least one of a high heat conductivity and heat resistance.
21. (Withdrawn) A module component according to claim 16, wherein said resin contains at least one of  $\text{Al}_2\text{O}_3$ ,  $\text{SiC}$ ,  $\text{Al}_3\text{N}_4$ , and  $\text{Si}_3\text{N}_4$  as a filler.
22. (Withdrawn) A module component according to claim 16, wherein said resin contains at least one of ceramic powder and  $\text{SiO}_2$  as a filler.

23. (Withdrawn) A module component according to claim 16, wherein said resin contains a magnetic material.
24. (Withdrawn) A module component according to claim 16, wherein said end electrode of said chip component and a surface of said molded element are formed in different colors.
25. (Withdrawn) A module component according to claim 16, wherein said molded element comprises a ground layer over a bottom of said molded element, and wherein said ground layer is directly coupled with said end electrode.
26. (Withdrawn) A module component comprising:
  - a chip component disposed according to a specified rule;
  - an IC chip mounted to one side of a molded element formed by resin;
  - a circuit wiring on a substrate for directly coupling an electrode terminal of said IC chip with said wiring patterns on said substrate through said chip component.
27. (Withdrawn) A manufacturing method of a module component comprising:
  - an inserting step of inserting a chip component in a molding die;
  - a primary molding step of filling the molding die with resin with an end electrode of the chip component exposed;
  - a peeling step of peeling the molding die at a side of inserting the chip component;
  - a secondary molding step of filling the molding die with resin with an end electrode of the chip component; and
  - a forming step of forming a circuit wiring on one side or both sides of a molded element molded with resin,

wherein the chip component is disposed according to a specified rule, and the chip component are molded with the resin to compose a desired circuit.

28. (Withdrawn) A manufacturing method according to claim 27, wherein the chip component is disposed in a specified position according to a matrix, and the chip component of a specific value is molded with the resin to compose a desired circuit.
29. (Withdrawn) A manufacturing method according to claim 28, wherein a dummy component having a same size as the chip component is inserted at a position where the chip component is not inserted according to the matrix.
30. (Withdrawn) A manufacturing method of a module component comprising:  
an inserting step of inserting a chip component in a molding die, the chip component being disposed according to a specified rule;  
a primary molding step of filling with resin with an end electrode of the chip component exposed;  
a peeling step of peeling the molding die at a side of inserting the chip component;  
a secondary molding step of filling with resin with an end electrode of the chip component exposed; and  
a step of mounting an IC chip on one side of a molded element molded with resin and coupling an other side to a substrate,  
wherein a electrode terminal of the IC chip is directly coupled with a circuit wiring on the substrate through the chip component.
31. (Currently amended) A module component comprising:  
a substrate made of resin having  $[[a]]$  penetration holes  $[[hole]]$ ;

circuit wirings [[wiring]] disposed on both sides of said substrate, respectively;  
a chip component having a height almost same as a depth of one of said  
penetration holes, and placed [[hole and put]] in [[the]] one of said penetration holes  
[[hole]] for electrically coupling said circuit wirings to each other; [[wiring disposed on  
both sides of said substrate; and]]

wherein said [[the]] penetration holes are [[hole is]] formed at positions [[a  
position]] according to a matrix,

[[wherein a chip component having a specific value is accommodated to compose  
a desired circuit,]] and

wherein said [[the]] penetration holes are [[hole is]] tapered.

32. (Currently amended) A module component comprising:

a substrate made of resin having [[a]] penetration holes [[hole]];

circuit wirings [[wiring]] disposed on both sides of said substrate, respectively;

a chip component having a height almost same as a depth of one of said  
penetration holes, and placed [[hole and put]] in [[the]] one of said penetration holes  
[[hole]] for electrically coupling said circuit wirings to each other [[wiring disposed on  
both sides of said substrate]]; and

a ground layer disposed beneath said substrate, said ground layer being coupled  
with one of said circuit wirings [[wiring]] disposed on a lower side of said substrate,

wherein the penetration holes are [[hole is]] formed at positions [[a position]]  
according to a matrix [[, and

wherein a chip component having a specific value is accommodated to compose a  
desired circuit]].



33. (Currently amended) A module component comprising:
- a substrate made of resin having a penetration hole;
  - circuit wirings [[wiring]] disposed on both sides of said substrate, respectively;
  - a chip component having a height almost same as a depth of said penetration hole, and placed [[and put]] in said [[the]] penetration hole for electrically coupling said circuit wirings to each other [[wiring disposed on both sides of said substrate]];
  - an auxiliary substrate disposed over said substrate; and
  - a ground layer disposed beneath said auxiliary substrate, said ground layer being coupled with one of said circuit wirings [[wiring]] disposed on a lower side of said substrate.
34. (Currently amended) A module component comprising:
- a substrate made of resin having [[a]] penetration holes [[hole]];
  - circuit wirings [[wiring]] disposed on both sides of said substrate, respectively;
  - a chip component having a height almost same as a depth of one of said penetration holes, and placed [[hole and put]] in one of said [[the]] penetration holes [[hole]] for electrically coupling said circuit wirings to each other [[wiring disposed on both sides of said substrate]];
  - an auxiliary substrate disposed over said substrate;
  - an IC chip mounted on said auxiliary substrate; and
  - a ground layer disposed beneath said auxiliary substrate,
  - wherein the penetration holes are [[hole is]] formed at a position according to a matrix, and
  - wherein said IC chip is coupled directly with said ground layer.

35. (Previously presented) A module component according to claim 1, further comprising a dummy component disposed in another penetration hole of said penetration holes, said dummy component having a size almost the same as said chip components and functioning as an insulator.